

Serial No.: 10/532,364  
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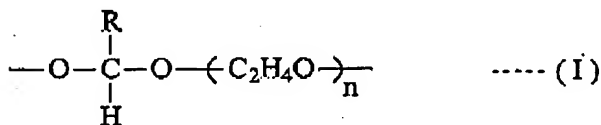
Complete set of claims

1(currently amended). A chemically amplified positive-working photosensitive resin composition, comprising (A) an alkali soluble novolak resin, (B) an alkali soluble acrylic resin, (C) an acetal compound, and (D) an acid generator further where the weight ratio of the components (A):(B):(C):(D) is 100 : (2 to 200) : (1 to 50) : (0.05 to 10), further where the acrylic resin contains a structural unit derived from hydroxyalkyl methacrylate and a structural unit derived from alkyl methacrylate, and optionally a structural unit derived from styrene.

2(canceled).

3(canceled).

4(previously amended). The chemically amplified positive-working photosensitive resin composition according to claim 1, wherein the acetal compound has a structural unit represented by the following general formula (I):



wherein R represents a saturated alkyl group having 1 to 20 carbon-atoms; and n is an integer of 1 to 10.

5(canceled).

6(previously amended). A coated substrate comprising a coating of the chemically amplified positive-working photosensitive resin composition of claim 1, wherein the coating has a film thickness of 5  $\mu\text{m}$  or more.

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7(currently amended). A process comprising imaging the chemically amplified positive-working photosensitive resin composition of claim 1 and followed by forming a cyan or non cyan electrolytic gold plating layer.

8(currently amended). A process comprising imaging the chemically amplified positive-working photosensitive resin composition of claim 1 and followed by forming a plating layer selected from copper, nickel and solder.

9(previously amended). The process of claim 7 wherein plating layer is a multilayer.

10(currently amended). The process of claim 8, wherein ~~the~~ the plating layer is a multilayer.

11(previously presented). The process of claim 9, where the multilayer comprises a gold layer and at least one additional layer selected from copper, nickel and solder.

12(previously presented). The process of claim 10, where the multilayer comprises at least one layer selected from copper, nickel and solder, and at least one additional layer comprising gold.